**WHAT IS CLAIMED IS:**

1. A device having a solid state power source, comprising:

a first frame having a first contact portion, a first bonding portion and a first extension portion between the first contact portion and the first bonding portion;

a second frame having a second contact portion, a second bonding portion and a second extension portion between the second contact portion and the second bonding portion; and

a first pole layer, a first electrolyte layer and a second pole layer positioned between the first and second contact portions,

wherein a first portion of the first electrolyte layer is positioned between the first extension and the first pole and a second portion of the first electrolyte layer is positioned between the first extension and the second pole.

2. The device according to claim 1, wherein a third portion of the first electrolyte layer is positioned between the first pole and the second pole.

3. The device according to any one of claims 1 or 2, wherein the first contact portion is attached to the first pole layer with a first conductive adhesive layer and the second contact portion is attached to the second pole layer with a second conductive adhesive layer.

4. The device according to any one of claims 1, 2 or 3, further comprising a third pole layer, a second electrolyte layer and a fourth pole layer positioned between the first and second contact portions.

5. The device according to any one of claims 1, 2, 3 or 4, wherein the first electrolyte layer, including the first and second portions, encapsulates the first and second poles.

6. The device according to any one of claims 1, 2, 3, 4, or 5, further comprising:

an electronic circuit, wherein the first bonding portion is electrically and mechanically bonded to the electronic circuit with a first conductive connection adhesive and the second bonding portion is electrically and mechanically bonded to the electronic circuit with a second conductive connection adhesive.

7. The device according to claim 6, further comprising

a third frame having a third contact portion, a third bonding portion and a third extension portion between the third contact portion and the third bonding portion;

a fourth frame having a fourth contact portion, a fourth bonding portion and a fourth extension portion between the fourth contact portion and the fourth bonding portion; and

a third pole layer, a second electrolyte layer and a fourth pole layer positioned between the third and fourth contact portions,

wherein the third bonding portion is electrically and mechanically bonded to the electronic circuit with a first conductive connection adhesive and the fourth bonding portion is electrically and mechanically bonded to the electronic circuit with a second conductive connection adhesive.

8. The device according to claim 7, wherein the first frame, second frame, third frame, fourth frame, first pole layer, first electrolyte layer, second electrolyte layer, second pole layer and electronic circuit are hermetically sealed in an enclosure.

9. The device according to any one of claims 1 – 8, further comprising:

first and second side encapsulant regions positioned between the first and second contact portions, and wherein the first and second contact portions are positioned between the first and second side encapsulant regions.

10. The device according to claim 9, wherein the first electrolyte layer is a composite including an electrolyte salt and a first polymer, and the first and second side encapsulant regions include a second polymer.

11. The device according to any one of claims 9–10, further comprising third and fourth side encapsulant regions positioned between the first and second contact portions such that the first, second, third and fourth encapsulant regions encircle the first and second poles.

12. The device according to any one of claims 1 – 5 or 9 – 11, further comprising:

a substrate having a first side and a second side;

an electronic circuit on the first side of the substrate,

wherein the first and second frames electrically and mechanically contact the electronic circuit on the first side of the substrate.

13. The device according to claim 12, further comprising a hermetic enclosure surrounding the first frame, second frame, first pole layer, first electrolyte layer, second electrolyte layer, second pole layer and electronic circuit.

**WHAT IS CLAIMED IS:**

1. A device having a solid state power source, comprising:

a first frame having a first contact portion, a first bonding portion and a first extension portion between the first contact portion and the first bonding portion;

a second frame having a second contact portion, a second bonding portion and a second extension portion between the second contact portion and the second bonding portion; and

a anode/cathode layer, a first electrolyte layer and a cathode/anode layer positioned between the first and second contact portions,

wherein a first portion of the first electrolyte layer is positioned between the first extension and the first pole and a second portion of the first electrolyte layer is positioned between the first extension and the second pole.

2. The device according to claim 1, wherein a third portion of the first electrolyte layer is positioned between the first pole and the second pole.

3. The device according to any one of claims 1 or 2, wherein the first contact portion is attached to the anode/cathode layer with a first conductive adhesive layer and the second contact portion is attached to the cathode/anode layer with a second conductive adhesive layer.

4. The device according to any one of claims 1, 2 or 3, further comprising a third pole layer, a second electrolyte layer and a fourth pole layer positioned between the first and second contact portions.

5. The device according to any one of claims 1, 2, 3 or 4, wherein the first electrolyte layer, including the first and second portions, encapsulates the first and second poles.

6. The device according to any one of claims 1, 2, 3, 4, or 5, further comprising:

an electronic circuit, wherein the first bonding portion is electrically and mechanically bonded to the electronic circuit with a first conductive connection adhesive and the second bonding portion is electrically and mechanically bonded to the electronic circuit with a second conductive connection adhesive.

7. The device according to claim 6, further comprising

a third frame having a third contact portion, a third bonding portion and a third extension portion between the third contact portion and the third bonding portion;

a fourth frame having a fourth contact portion, a fourth bonding portion and a fourth extension portion between the fourth contact portion and the fourth bonding portion; and

a third pole layer, a second electrolyte layer and a fourth pole layer positioned between the third and fourth contact portions,

wherein the third bonding portion is electrically and mechanically bonded to the electronic circuit with a first conductive connection adhesive and the fourth bonding portion is electrically and mechanically bonded to the electronic circuit with a second conductive connection adhesive.

8. The device according to claim 7, wherein the first frame, second frame, third frame, fourth frame, anode/cathode layer, first electrolyte layer, second electrolyte layer, cathode/anode layer and electronic circuit are hermetically sealed in an enclosure.

9. The device according to any one of claims 1 – 8, further comprising:

first and second side encapsulant regions positioned between the first and second contact portions, and wherein the first and second contact portions are positioned between the first and second side encapsulant regions.

10. The device according to claim 9, wherein the first electrolyte layer is a composite including an electrolyte salt and a first polymer, and the first and second side encapsulant regions include a second polymer.

11. The device according to any one of claims 9 –10, further comprising third and fourth side encapsulant regions positioned between the first and second contact portions such that the first, second, third and fourth encapsulant regions encircle the first and second poles.

12. The device according to any one of claims 1 – 5 or 9 – 11, further comprising:

a substrate having a first side and a second side;

an electronic circuit on the first side of the substrate,

wherein the first and second frames electrically and mechanically contact the electronic circuit on the first side of the substrate.

13. The device according to claim 12, further comprising a hermetic enclosure surrounding the first frame, second frame, anode/cathode layer, first electrolyte layer, second electrolyte layer, cathode/anode layer and electronic circuit.

14. The device according to claim 1 wherein the first and second portions of the first electrolyte layer are both directly below the first contact portion of the first frame.

15. The device according to claim 1 or claim 14 wherein the anode/cathode layer and cathode/anode layer are part of a stack that is directly between the first and second contact portions of the first and second frames.